

Application Data Sheet

Application Information	
Application Number::	not assigned
Filing Date::	not assigned
Application Type::	Regular
Subject Matter::	Utility
Suggested Classification::	
Suggested Group Art Unit::	
Title::	Method and Apparatus for Examining Semiconductor Wafers in a Context of Die/Saw Design
Attorney Docket Number::	21295.74 (H5742US)
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	3
Total Drawing Sheets::	3
Small Entity?::	No
Licensed US Govt. Agency::	
Contract or Grant Numbers::	
Secrecy Order in Parent Appl.?::	

Applicant Information	
Applicant Authority Type::	Inventor
Primary Citizenship Country::	Germany
Status::	Full Capacity
Given Name::	Detlef
Middle Name::	
Family Name::	Michelsson
Name Suffix::	
City of Residence::	Wetzlar-Naunheim
State or Province of Residence::	
Country of Residence::	Germany
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State or Province of mailing address::	
Country of mailing address::	Germany
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Correspondence Information	
Correspondence Customer Number::	29127

Representative Information	
Representative Customer Number::	29127

Foreign Priority Information			
Country::	Application number::	Filing Date::	Priority Claimed::
Germany	DE10307373.6	02/21/2003	Yes

Assignee Information	
Assignee Name::	Leica Microsystems Semiconductor GmbH
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State or Province of mailing address::	
Country of mailing address::	Germany
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